

Product Change Notice (PCN)

Subject: Package Outline Correction for 10L / MSOP-EP

Publication Date: 11/11/2019

Effective Date: 2/9/2020

Revision Description:

Initial Release

Description of Change:

Renesas Electronics America Inc has updated 10 leads EP-MSOP (Exposed Pad Mini Small Outline Package). The updates include changes to the following:

10L / MSOP - Exposed Pad

Package Outline Description	Symbol	From		To	
		Min (mm)	Max (mm)	Min (mm)	Max (mm)
Package Standoff height	A1	0.025	0.100	0.050	0.150

Affected Product List

ISL1557IUEZ	ISL1571IUEZS2711
ISL1557IUEZ-T7	ISL1571IUEZS2769
ISL1571IUEZ	ISL1572IUEZ
ISL1571IUEZ-T7	ISL1572IUEZ-T7
ISL1571IUEZ-T7S2711	
ISL1571IUEZ-T7S2769	

Reason for Change:

The correction to the package outline aligns the documentation with the product characteristics.

Impact on fit, form, function, quality & reliability:

Form is affected. The change will have no impact on the fit, function, quality, reliability and environmental compliance of the devices.

Product Identification:

Product affected by this change is identifiable via Renesas's internal traceability system.

Qualification status: Complete, see attached

Sample availability: 11/11/2019

Device material declaration: Available upon request

Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Intersil within 30 days of the publication date.

For additional information regarding this notice, please contact your regional change coordinator (below)			
Americas: PCN-US@Renesas.COM	Europe: PCN-EU@Renesas.COM	Japan: PCN-JP@Renesas.COM	Asia Pac: PCN-APAC@Renesas.COM

Appendix A – Package Outline Drawing (POD) 10 Leads / MSOP – Exposed Pad

Standoff height is listed in Detail “A”.

